



Material Content Data Sheet



Sales Product Name		ICE3RBR4765JG		Issued		20. July 2018			
MA#		MA001580086							
Package		PG-DSO-12-19		Weight*		154.91 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.867	1.21	1.21	12053	12053	
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112		
	non noble metal	zinc	7440-66-6	0.069	0.04		447		
	non noble metal	iron	7439-89-6	1.386	0.89		8948		
wire	non noble metal	copper	7440-50-8	56.286	36.33	37.27	363342	372849	
	noble metal	gold	7440-57-5	0.215	0.14	0.14	1385	1385	
	encapsulation	organic material	carbon black	1333-86-4	0.278	0.18		1794	
encapsulation	plastics	epoxy resin	-	10.836	7.00		69952		
	inorganic material	silicondioxide	60676-86-0	81.504	52.61	59.79	526131	597877	
leadfinish	non noble metal	tin	7440-31-5	1.143	0.74	0.74	7376	7376	
plating	noble metal	silver	7440-22-4	0.428	0.28	0.28	2766	2766	
glue	plastics	epoxy resin	-	0.132	0.09		854		
	noble metal	silver	7440-22-4	0.750	0.48	0.57	4840	5694	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com